WinWay *Your Trusted Partner in Semiconductor Testing*

TWSE:6515

Investor Presentation

2026.10.19

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Company Information

Founded

2001.4 .10

Capital Stock

NTD 364,447,820

Employees

1602

Chairman & CEO

Mark Wang

Business Operation

Design, manufacture, sale and service of test interface products

Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist. Kaohsiung City, Taiwan

Kaohsiung Headquarter

USA Branch Office

Hsinchu Branch Office

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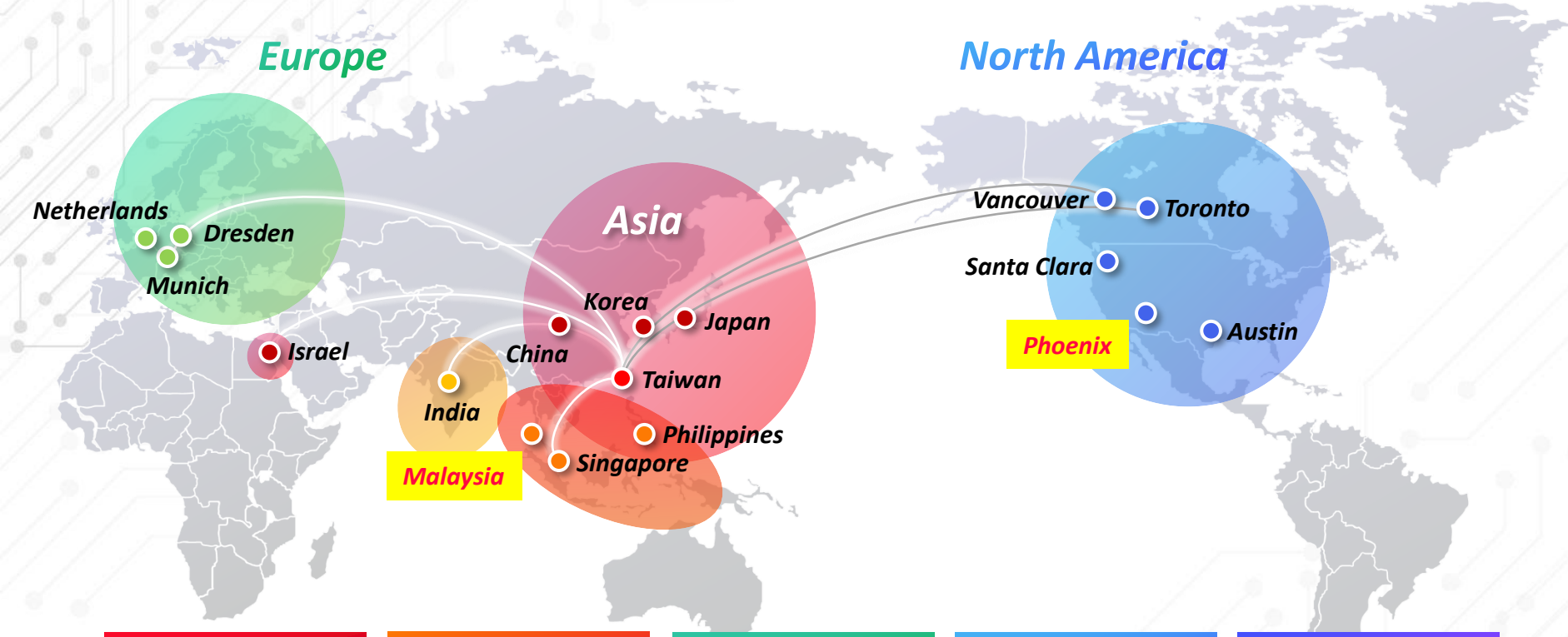
Global Service & Support Network



KH Spring Probe	KH Plant	Hsinchu Plant	Suzhou Plant	Renwu Plant
Spring Probe for Socket	Coaxial Socket HyperSocket™	Vertical Probe Card MEMS Probe Card	Coaxial Socket	Coaxial Socket

WinWay

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Accelerating Expansion
Socket Capacity

Renwu Facility I

Operational from May. 2026

Renwu Facility II

Ground-breaking : 2026.5.29

Begin Operation : 2027 Q2

Total Area
Approx. **6300** *ping*

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Accelerating Expansion Spring Probe Capacity

Cost Optimization

Balanced insourcing, better cost structure

Self-Sufficiency

Autonomy of critical process technology

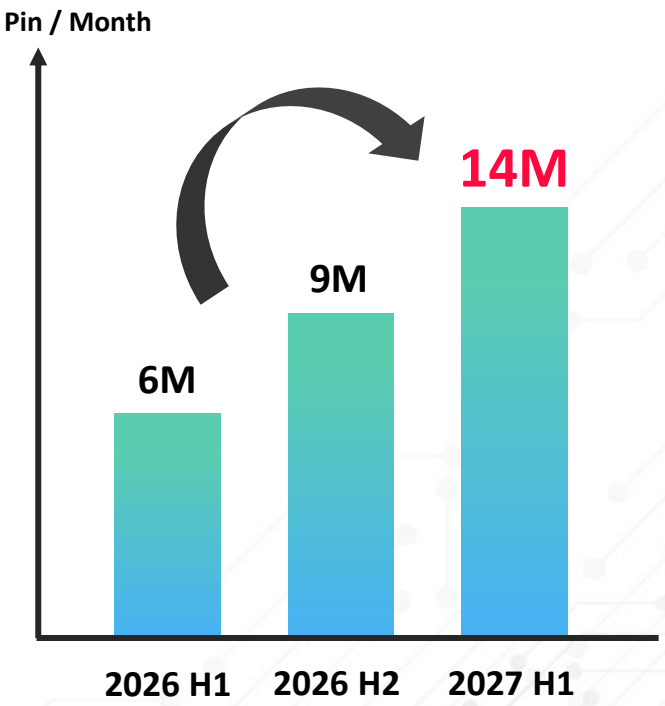
Quality Assurance

Greater customer experience

Operational Resilience

More flexible, agile lead time

WinWay Spring Probe Capacity



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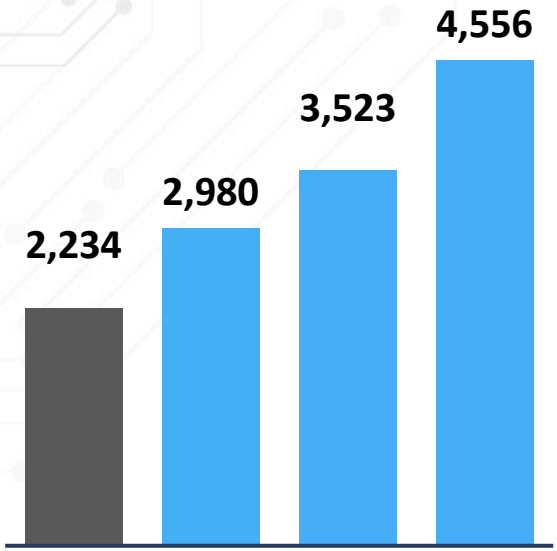
Revenue Trend

QUARTERLY REVENUE

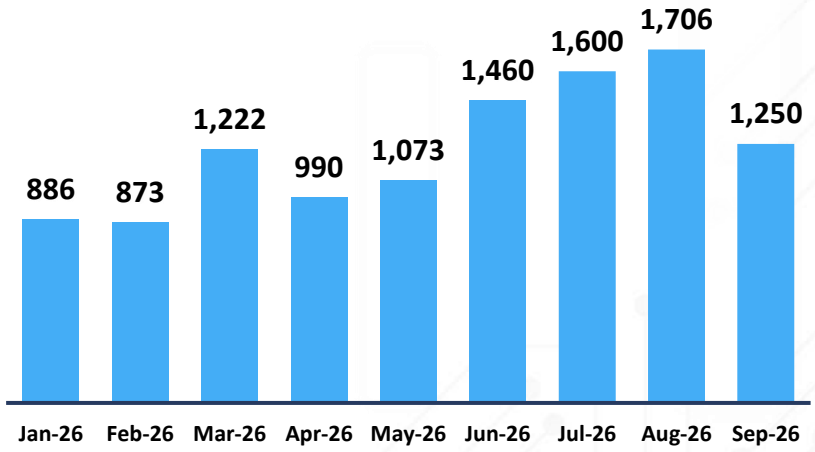
(NTD MILLION)



	4Q25	1Q26	2Q26	3Q26
YoY	45%	30%	131%	153%
QoQ	24%	33%	18%	29%

MONTHLY REVENUE

(NTD MILLION)



	Jan-26	Feb-26	Mar-26	Apr-26	May-26	Jun-26	Jul-26	Aug-26	Sep-26
YoY	33%	-4%	69%	51%	120%	288%	156%	233%	88%
MoM	-5%	-2%	40%	-19%	8%	36%	10%	7%	-27%

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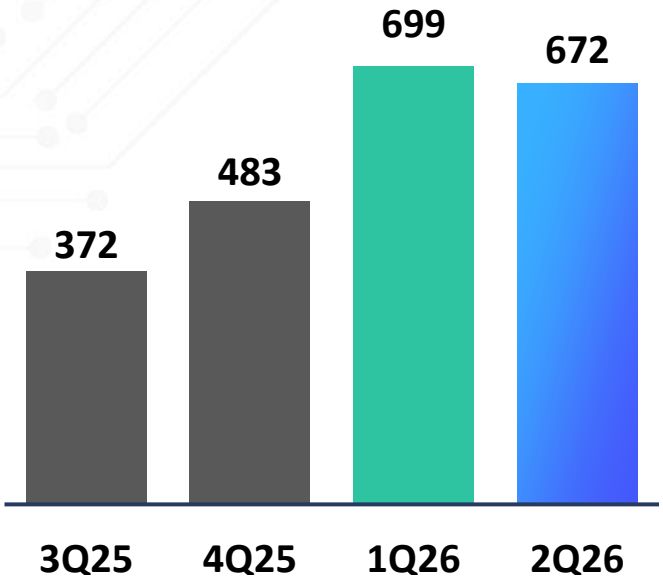
Profitability Trend

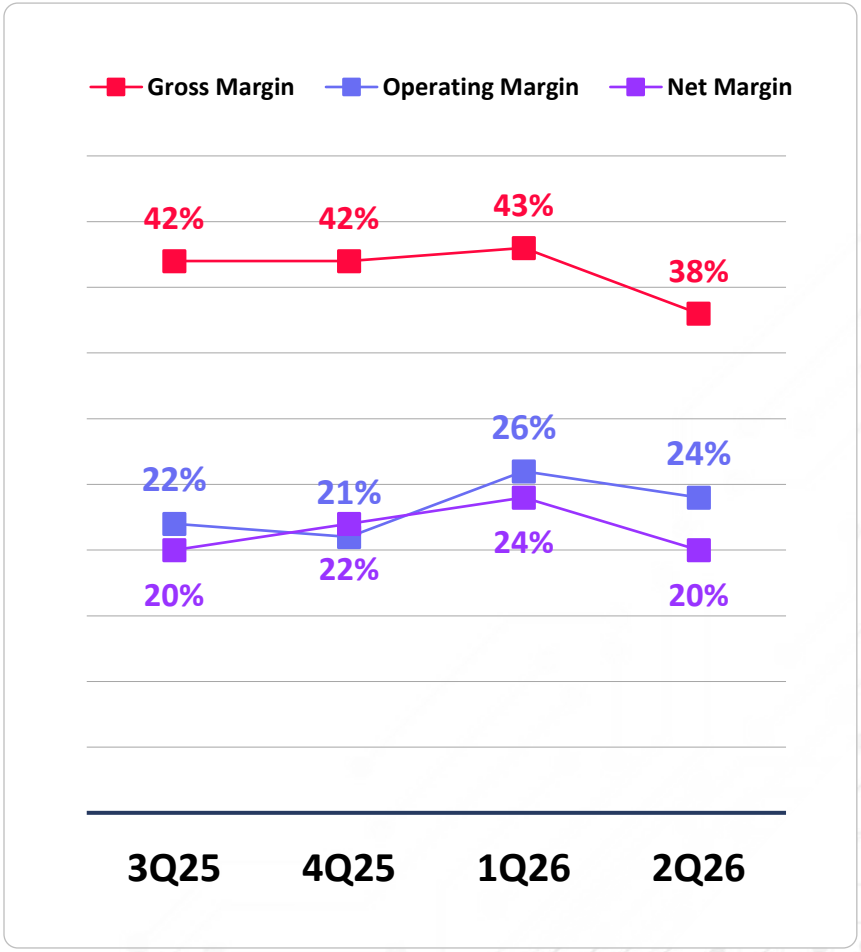
2026 Q1-Q2 EPS

(NT$) **38.24**

EPS	10.43	13.53	19.54	18.7

NET INCOME (NTD M)





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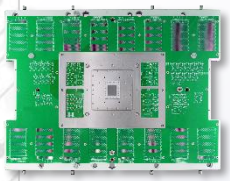
Revenue by Product Mix

2026 H1



Probe Card

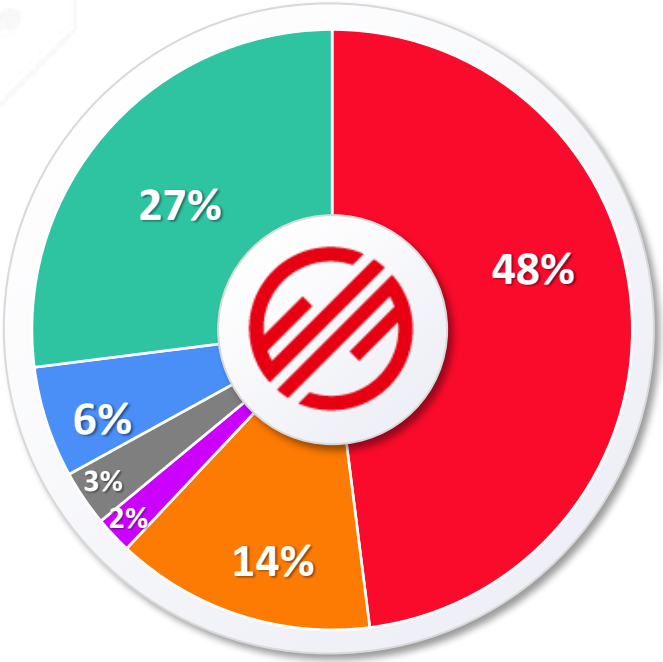
27%

Contact Element

6%

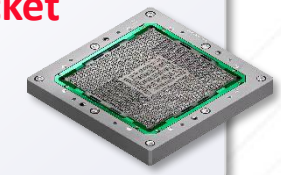
Others

3%



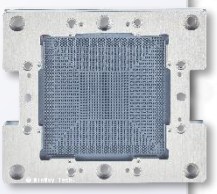
Coaxial Socket

48%



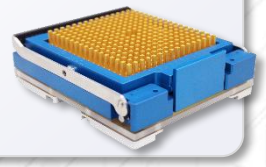
PoP & Plastic Socket

14%



Burn-in Socket

2%



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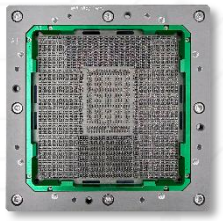
Revenue by End Market

2026 H1

HyperSocket™



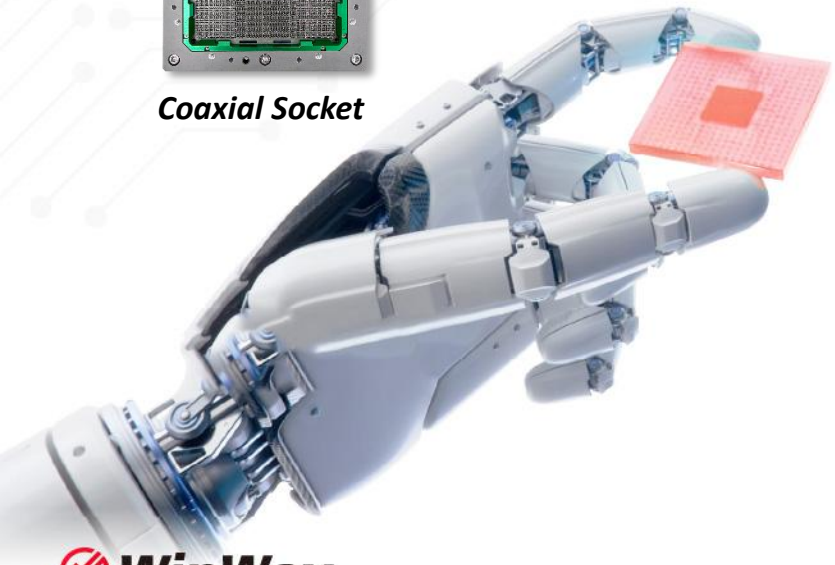
Coaxial Socket

HPC & AI
70%

Networking Auto / Others
18%
Plastic Socket

Smart Phone
8%
POP Plastic Socket

PC & Gaming
4%
POP Plastic Socket



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In for the Long Haul

GPU

TPU

CPU

AI ASIC

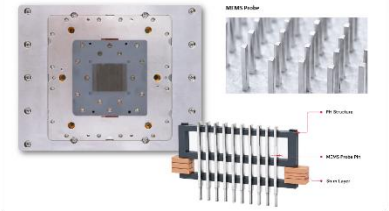
Automotive

Edge Computing

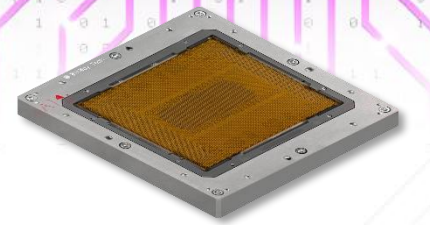
High Speed Networking

Smart Phone

Customer Approach



MEMS Probe Card



HyperSocket™

Functional Burn-in

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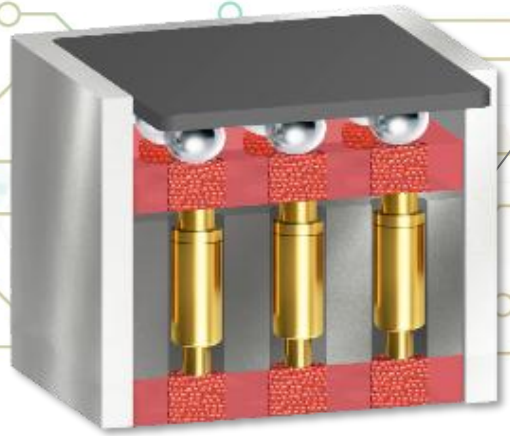
Innovative Semiconductor Test Interface Solution

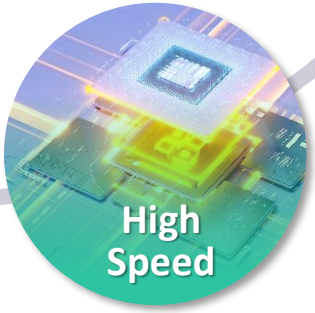
HyperSocket™-Dual Film

Patent NO.	Patent Pending
TWI862047	USA
TWI884802	Malaysia
TWI862191	
TWI901161	
TWI922268	
TWI923382	
CN220584352	



- Larger contact area
- Improved heat dissipation
- Enhanced test stability

- Various current pathways
- Mitigating temperature rise



- Full metal shielding, short-loop design
- Test speed above 224Gbps

- Zero Pre-load design
- Reduced maintenance cost

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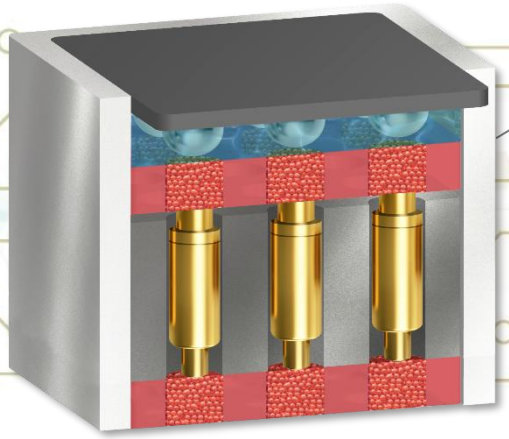
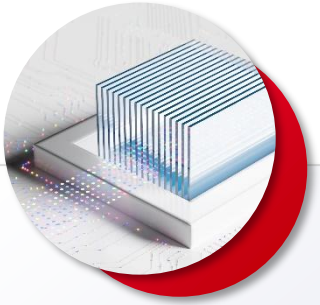
Innovative Semiconductor Test Interface Solution

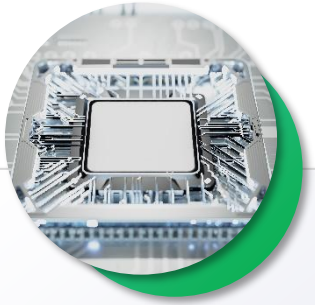
Liquid Cooling Socket



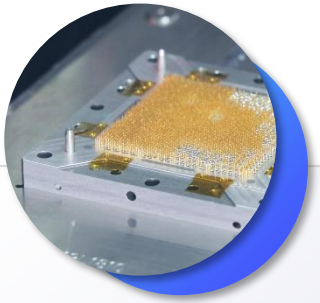
Patent NO.
TWI901181
US12625162



Extraordinary heat dissipation



Improved Test Stability For Advanced Packaging



Extend Spring Probe Lifespan

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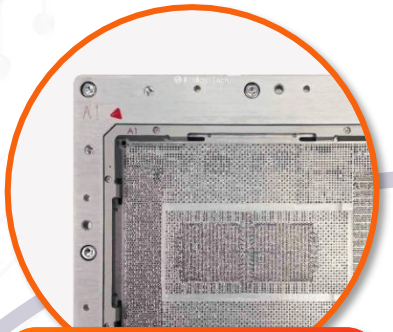
Accelerated SLT Demand Driven by AI

Comprehensive solution for all test insertions

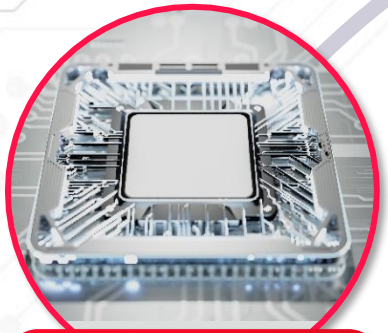


High Pin Count

>20KPin

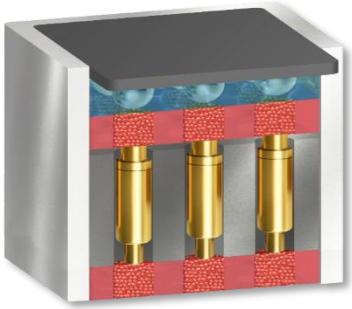
High-Speed Testing

>224Gbps



Ultra Large Package

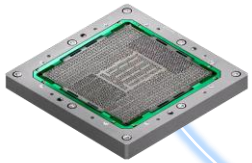
>100X100mm²



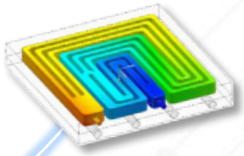
HyperSocket™

High Heat Density

>4000W



Coaxial Socket



Thermal System

Functional Burn-in

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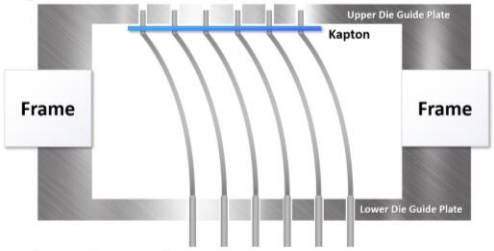
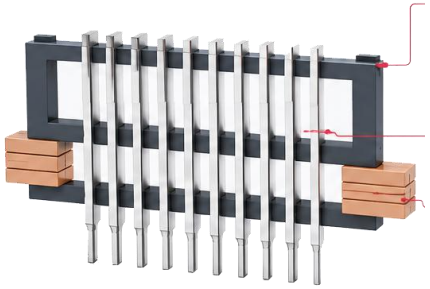
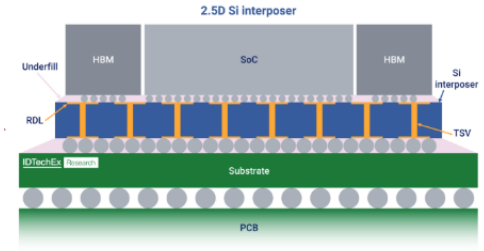
Greater Importance on Chip Probing

At Speed Test and K.G.D



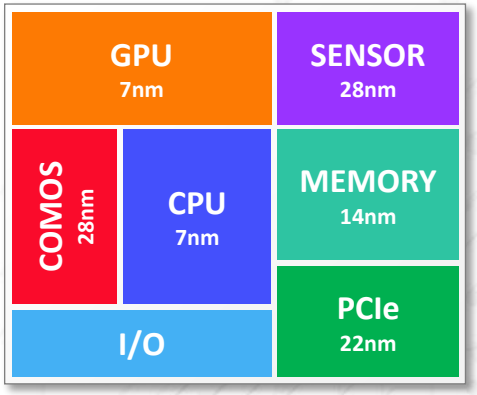




Source : IDTechEx Research

	Cobra	*MEMS*
Pin Count	Less, limited to probe force design	★ **Higher (More flexible to design)**
CCC(A)	2.2 @ 4mil probe diameter	★ **2.2 @ 3mil probe diameter**
High Speed	32G	★ **112G**
Force(g)	2~25	★ **1.5 ~ 4.5**
Pitch (um)	80~200	★ **40~200**
Operating Temp.	- 50℃ to 150℃	★ **- 50℃ to 175℃**

Chiplet **Multiple Probe Card Demand**



Source : Trend Force

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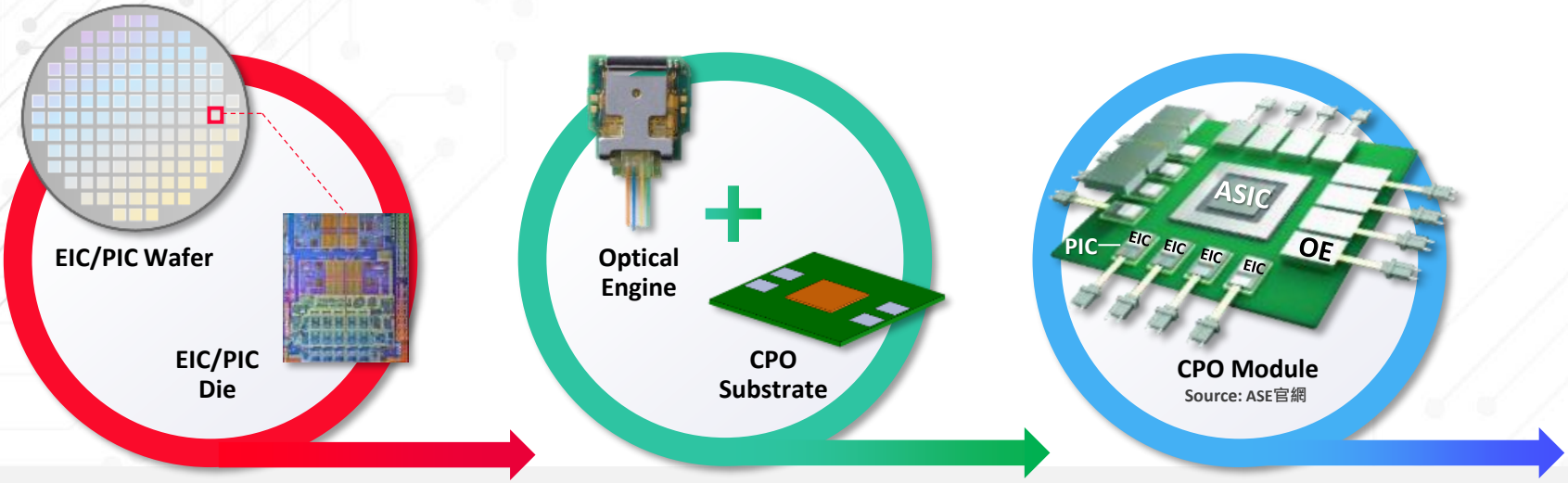
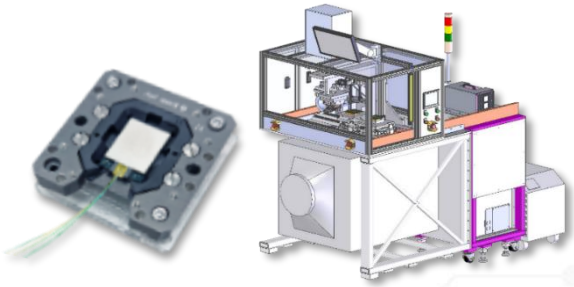
Co-Packaged Optics Test Solution

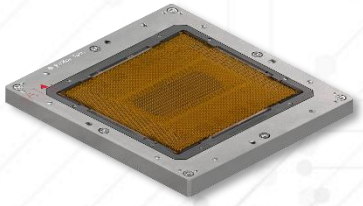


WLCSP Probe Head
(PIC & EIC Wafer test)



Optical and Electrical Test Socket
(Optical Engine)

Double Sided Probing System



HyperSocket™

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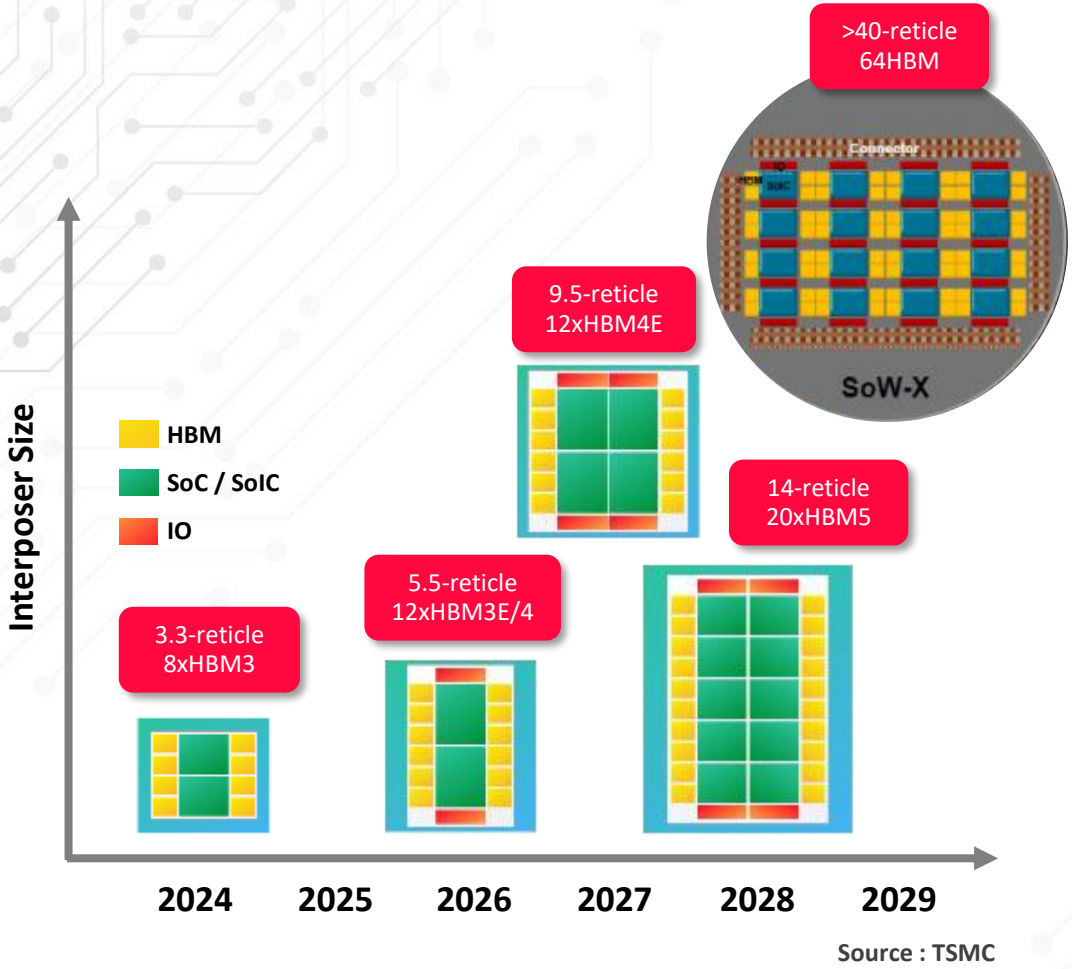
Performance Breakthrough: Evolution of Advanced Packaging

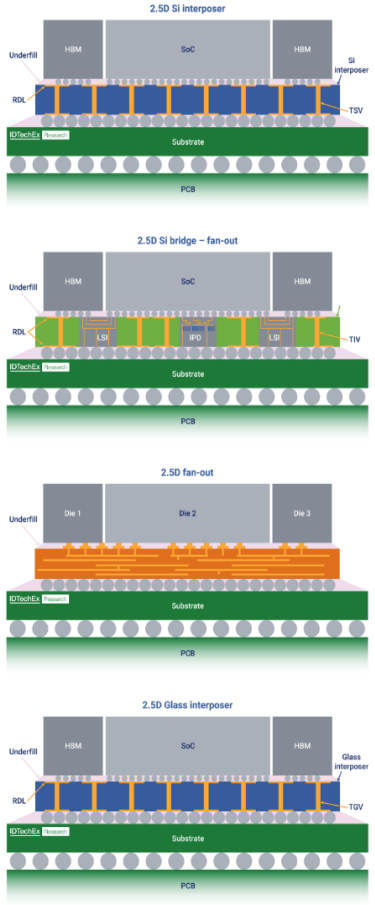


Source : TSMC

Si-based Interposer

Organic-based Interposer

Glass-based Interposer



Source : IDTechEx Research

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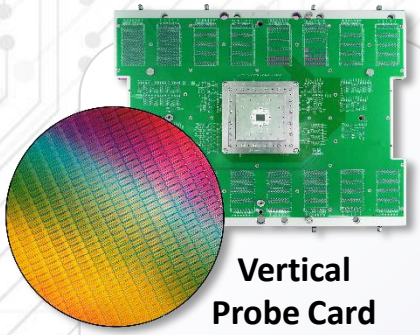
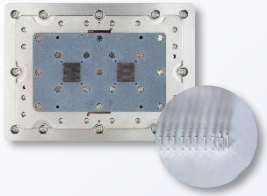
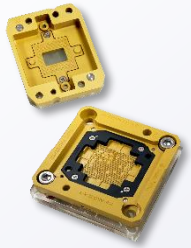


Vertical Probe Card

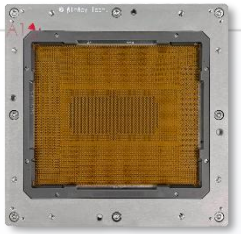


MEMS Probe Card

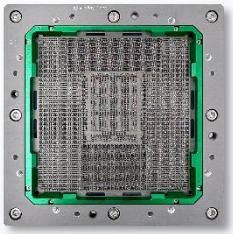
Coaxial Socket



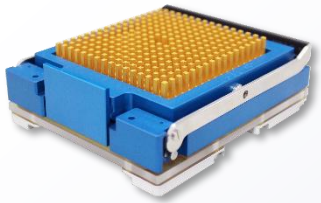
PoP Socket



HyperSocket™



Coaxial Socket



Production Burn-in Socket

Wafer Sort → **Final Test** → **SLT & SFT** → **Functional Burn-in**

DFT Design For Testing **DFM** Design For Manufacturing

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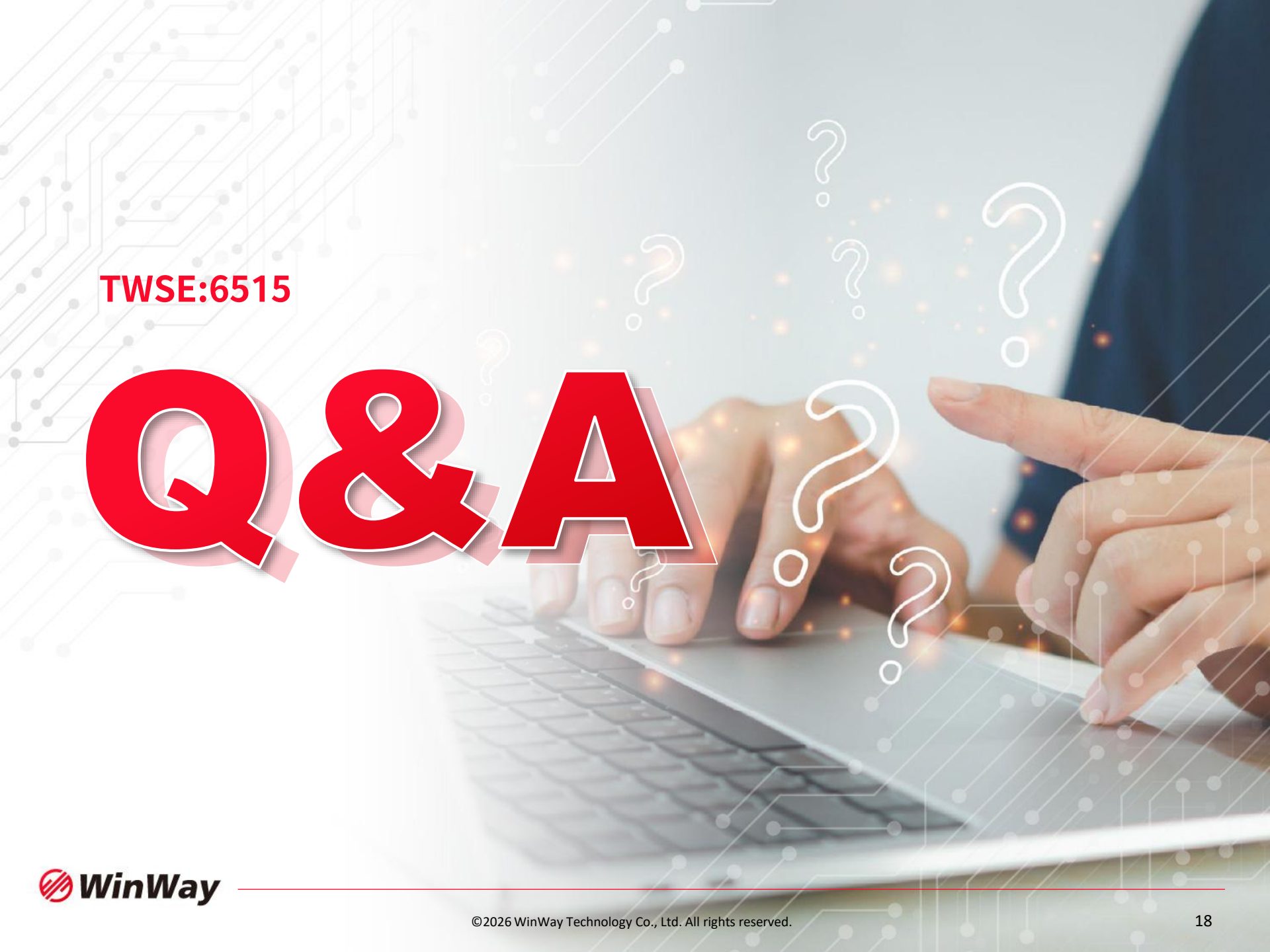
Q&A



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THANK YOU

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